

[METAL BONDING METHOD FOR SEMI- CONDUCTOR CIRCUIT COMPONENTS EMPLOYING PRESCRIBED FEEDS OF METAL BALLS]

Abstract

A method for fabricating metal bonding for a semiconductor circuit component employing prescribed feed of metal ball is disclosed. The method comprises the steps of, first, placing a metal ball at the metallization site on the surface of the circuit die of the component; then, melting the metal ball on the site; and subsequently solidifying the molten metal and forming a metal bump at the site. A circuit die having formed with one or more metal bumps can then be made into a circuit component featuring stable and reliable electrical leads and suitable to be utilized as large power rating yet with reduced component size in electronic equipment.